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<input type="checkbox"/>	2. <b>Transient analysis of lossy transmission lines: An efficient approach based on the method of characteristics</b> By: Grivet-Talocia, S; Huang, HM; Ruehli, AE; et al. Conference: IEEE 11th Topical Meeting on Electrical Performance of Electronic Packaging Location: MONTEREY, CA Date: OCT 21-23, 2002 Sponsor(s): IEEE Microwave Theory & Techn Soc; IEEE Components, Packaging & Mfg Technol Soc IEEE TRANSACTIONS ON ADVANCED PACKAGING Volume: 27 Issue: 1 Pages: 45-56 Published: FEB 2004	2	3	4	2	0	77	5.50
<input type="checkbox"/>	3. <b>M pi log, macromodeling via parametric identification of logic gates</b> By: Stievano, IS; Maio, IA; Canavero, FG Conference: IEEE 11th Topical Meeting on Electrical Performance of Electronic Packaging Location: MONTEREY, CA Date: OCT 21-23, 2002 Sponsor(s): IEEE Microwave Theory & Techn Soc; IEEE Components, Packaging & Mfg Technol Soc IEEE TRANSACTIONS ON ADVANCED PACKAGING Volume: 27 Issue: 1 Pages: 15-23 Published: FEB 2004	3	3	5	6	1	58	4.14
<input type="checkbox"/>	4. <b>Parameters Variability Effects on Multiconductor Interconnects via Hermite Polynomial Chaos</b> By: Stievano, Igor Simone; Manfredi, Paolo; Canavero, Flavio G. IEEE TRANSACTIONS ON COMPONENTS PACKAGING AND MANUFACTURING TECHNOLOGY Volume: 1 Issue: 8 Pages: 1234-1239 Published: AUG 2011	10	8	8	10	1	47	6.71

- ☐ 5. **Parametric macromodels of digital I/O ports**  
 By: Stievano, IS; Maio, IA; Canavero, FG  
 Conference: 10th Topical Meeting on Electrical Performance of Electronic Packaging Location: CAMBRIDGE, MA Date: OCT 29-31, 2001  
 Sponsor(s): IEEE Microwave Theory & Techn Soc; IEEE Components, Packaging & Mfg Technol Soc  
[IEEE TRANSACTIONS ON ADVANCED PACKAGING](#) Volume: 25 Issue: 2  
 Pages: 255-264 Published: MAY 2002
- ☐ 6. **Stochastic Modeling-Based Variability Analysis of On-Chip Interconnects**  
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 Published: JUL 2012
- ☐ 7. **Stochastic Analysis of Multiconductor Cables and Interconnects**  
 By: Stievano, Igor S.; Manfredi, Paolo; Canavero, Flavio G.  
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[IEEE TRANSACTIONS ON ELECTROMAGNETIC COMPATIBILITY](#) Volume: 38 Issue: 3 Pages: 469-477 Published: AUG 1996
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 By: Wu, Tzong-Lin; Buesink, Frits; Canavero, Flavio  
[IEEE TRANSACTIONS ON ELECTROMAGNETIC COMPATIBILITY](#) Volume: 55 Issue: 4 Pages: 624-638 Published: AUG 2013
- ☐ 10. **Analysis of crosstalk and field coupling to lossy MTL's in a SPICE environment**  
 By: Maio, I; Canavero, FG  
[IEEE TRANSACTIONS ON ELECTROMAGNETIC COMPATIBILITY](#) Volume: 38 Issue: 3 Pages: 221-229 Published: AUG 1996

1	0	2	1	0	45	2.81
12	12	11	4	0	44	7.33
4	9	11	10	1	40	5.71
5	4	1	6	0	37	1.68
0	5	17	12	0	34	6.80
2	0	0	0	0	27	1.23

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